

**AMENDMENTS TO THE SPECIFICATION**

Please substitute the following amended paragraph for the pending paragraph beginning on page 1, line 12.

Such a device, and such an assembly, are described in ~~non~~-published patent application US 2005/0514917 ~~IB03/01343 (PHNL020718)~~. The assembly described therein is a camera module comprising, as the electric element, an image-processing semiconductor device (image sensor) and, in addition, a lens provided on the second side of the device. By virtue of the electric conductors anchored in the body, a compact device is obtained. Said body also is the carrier of the lens and the semiconductor device. In addition, the device makes it possible to apply further integration of functionality.

Please substitute the following amended paragraph for the pending paragraph beginning on page 5, line 6.

A particularly advantageous embodiment of the device is characterized in that the conductors comprise a first, a second and a third layer, the bonding pad portions being present in the third layer, and patterns in the second layer extending parallel to the first side having a smaller section than corresponding patterns in the first layer, and the electrically insulating material extending into cavities between the patterns in the second layer, thereby mechanically anchoring the corresponding patterns in the first layer. A body comprising such conductors composed of at least three layers is known, for example, from US 7, 247,938 ~~the non-published application WO-IB03/01299 (PHNL021100)~~, which is enclosed herein by reference. In said application, the first and the third layer contain copper and the second layer contains, for example, nickel, chrome, aluminum or an aluminum alloy. Advantageously, bonding layers, customarily composed of NiAu or NiPd, are present at the surface of the first and the third layer. If the body does not contain components, a bonding layer at the first layer is not necessary.

Please add the following new paragraph at page 11, line 30.

The invention has been described with reference to the preferred embodiments. Modifications and alterations will occur to others upon a reading and understanding of the preceding detailed description. It is intended that the invention be construed as including all such modifications and alterations insofar as they come within the scope of the appended claims or the equivalents thereof.